

AOS Semiconductor Product Reliability Report

AOZ17517QI-02 rev A

Plastic Encapsulated Device

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The AOS product reliability report summarizes the qualification results for AOZ17517QI-02 in QFN5x5A 32L package. Accelerated environmental tests are performed on a specific sample size, samples are electrically tested before and after each stress time point. Review of final electrical test results confirm that AOZ17517QI-02 pass the AOS guality and reliability requirements. The released products will be categorized by its process family and routinely monitored for continuous improvement of product quality.

Test Item	Test Condition	Time Point	Sample Size / Lots	Number of Failures	Reference Standard
HTOL	T」= 125°C, V _{IN} = 24V	168 / 500 / 1000 hours	231 pcs (3 lots)	0	JESD22-A108
Preconditioning (Note A)	TA = 30°C, RH = 60% + 3 cycle reflow @ 260°C (MSL 3)	192 hours	924 pcs (3 lots)	0	JESD22-A113
HAST	T _A = 130°C, RH = 85%, P = 33.3psia, V _{IN} = 20V	96 hours	231 pcs (3 lots)	0	JESD22-A110
Temperature Cycle	T _A = -65°C to 150°C, air to air	500 / 1000 cycles	231 pcs (3 lots)	0	JESD22-A104
HTSL	T _A = 150°C	1000 hours	231 pcs (3 lots)	0	JESD22-A103
Autoclave	T _A = 121°C, RH = 100%, P =29.7psia	96 hours	231 pcs	0	JESD22-A102
HTGB (MOSFET)	T _J = 150°C, V _{GS} = 10V	168 / 500 /1000 hours	231 (3 lots)	0	JESD22-A108
HTRB (MOSFET)	TJ = 150°C, VDS = 28.5V	168 / 500/1000 hours	231 (3 lots)	0	JESD22-A108

I. AOZ17517QI-02 Reliability Stress Test Summary and Results

Note: The reliability data presents total of available generic data up to the published date. Note A: MSL (Moisture Sensitivity Level) 3 based on J-STD-020

II. Reliability Evaluation

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the product technology. Failure Rate Determination is based on JEDEC Standard JESD 85.

FIT rate (failures per billion device hours): 1.393

MTTF = 717.9 million hrs=81952.622 years

Condition: $V_0 = 20V$, $T_0 = 55^{\circ}C$, $V_{s(IC)} = 24V$, $V_{s(MOSFET)} = 28.5V$, $T_{s(IC)} = 125^{\circ}C$ and $T_{s(MOSFET)} = 150^{\circ}C$ Accumulated Sample Size x Hours: MOSFET = 480,000, IC = 1,240,320

$\lambda = \chi^2$ [CL,(2f+2)]/2 x [1/(SS x t x AF)]; [equation 1] where CL = % of confidence level	
f = number of failure SS = sample size t = stress time	

Looking up the $\chi^2/2$ table for zero failure (burn-in) with 60% confidence, the value of χ^2 [CL,(2f+2)]/2 is 0.92.

The Acceleration Factor (AF) is calculated from the following formula (both temperature and voltage acceleration factors are used in the final acceleration factor calculation) : E_a = activation energy

 $AF = AF_T \times AF_V = \exp[(E_a/k) \times (1/T_0-1/T_s)] \times \exp[\beta (Vs-Vo)]$ where



- k = Boltzmann constant
- $T_o = operating T_J$
- $T_s = stress T_J$
- V_s = stress voltage
- V_{\circ} = operating voltage
- β = voltage acceleration coefficient

Assuming typical operating environment, $V_0 = 20V$, $T_0 = 55^{\circ}C$, $E_a = 0.7eV$, $V_{s(IC)} = 24V$, $V_{s(MOSFET)} = 28.5V$, $T_{s(IC)} = 125^{\circ}C$ and $T_{s(MOSFET)} = 150^{\circ}C$, $\beta = 0.5$ (silicon defect)

$$AF(DriverIC) = exp\left[\left(\frac{0.7}{8.617E - 5}\right) \bullet \left(\frac{1}{273 + 55} - \frac{1}{273 + 125}\right)\right] \bullet exp\left[0.5 \bullet (24V - 20V)\right]$$
$$AF(MOSFET) = exp\left[\left(\frac{0.7}{8.617E - 5}\right) \bullet \left(\frac{1}{273 + 55} - \frac{1}{273 + 150}\right)\right] \bullet exp\left[0.5 \bullet (28.5V - 20V)\right]$$

Substituting the values in equation 1, we have

$$\lambda = 0.92 \bullet \frac{1}{\text{sample Size} \bullet \text{Stress Duration} \bullet AF(MOSFET)} + \frac{1}{\text{sample Size} \bullet \text{Stress Duration} \bullet AF(DriverIC)} hr^{-1}$$

 λ = 1.393 10⁻⁹ hr ⁻¹ or 1.393 FIT; MTTF = (1/ λ) = 717.9 million hrs = 81952.622 years

The calculation shows failure rate is 1.393 FIT, MTTF is 717.9 million hours under typical operating conditions.

III. AOZ17517QI-02 ESD and Latch Up Test Results

Test	Test Conditions	Total Sample Size	Number of Failures	Reference Standard
Electrostatic Discharge Human Body Model	T _A = 25°C, +/-2kV	10	0	JESD-A114
Electrostatic Discharge Charged Device Model	T _A = 25°C, +/-1kV	10	0	JESD-C101
Latch Up	T _A = 25°C, +/-200mA, 1.27x OV	10	0	JESD78
Latch Up	T _A = 125°C, +/-200mA, 1.27x OV	10	0	JESD78

Note: ATE results are used to determine PASS/FAIL. Parametric shift<10%.

